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DS  
J. mitchell  
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IR-2156 (2-2817)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
Mario MERLIN, et al.  
Serial No.: 10/057,399  
Filed: January 25, 2002

New York, New York  
Date: December 24, 2002  
Group Art Unit: 2827  
Examiner: J. M. Mitchell

For: COMPRESSION ASSEMBLED ELECTRONIC PACKAGE HAVING A  
PLASTIC MOLDED INSULATION RING

Assistant Commissioner for Patents  
Washington, D.C. 20231

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TECHNOLOGY CENTER 2800  
JAN - 8 2003

SUBMISSION

Sir:

Submitted herewith is a copy of art together with a form listing the same for the convenience of the Examiner.

I respectfully request that the information submitted be considered and enclose our check number 14633 in payment of the required \$180.00 fee.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee due during the pendency of this application is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on December 26, 2002:

Kourosh Salehi

Name of applicant, assignee or  
Registered Representative

Kourosh Salehi

Signature

December 26, 2002

Date of Signature

Respectfully submitted,

Kourosh Salehi

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